

Frequently Asked Questions

Q: What is the primary difference between the Bond-Ply 660B and Bond-Ply 100 products?

A: Bond-Ply 660B utilizes a dielectric film, replacing the fiberglass inherent in our Bond-Ply 100 series products. The addition of the film allows for high dielectric performance without additional product thickness.

Q: How should I size my interface dimensions for Bond-Ply?

A: Bond-Ply product testing has been completed on various interface materials. These tests have demonstrated that improper surface wet-out is the single largest variable associated with maximizing bond strength and heat transfer. Bergquist has found that reducing the size of the interface pad to roughly 80% of the total interface area actually improves the overall bonding performance while offering significant improvements in total package cooling. Bergquist offers three standard thicknesses for Bond-Ply 100 allowing each application to be optimized in three dimensions.

Q: What application pressure is required to optimize bond strength with Bond-Ply?

A: The answer to this varies from application to application, depending upon surface roughness and flatness. In general, pressure, temperature, and time are the primary variables associated with increasing surface contact or wet-out. Increasing the application time and/or pressure will significantly increase surface contact. Natural wet-out will continue to occur with Bond-Ply materials. This inherent action often increases bond strength by more than 2x within the first 24 hours.

Q: Will Bond-Ply adhere to plastic packages?

A: Adhesive performance on plastic packages is primarily a function of surface contact or wet-out. If surface contaminants such as plastic mold release oils are present, this will prevent contact and/or bonding to the surface. Make sure all surfaces are clean and dry prior to applying Bond-Ply materials.

Q: How are one-part Liqui-Bond adhesives cured?

A: One-part Liqui-Bond requires heat to cure and bond in the application. Altering the bond line temperature and time can control the cure schedule. Component fixturing may be required to maintain placement through cure.

Bond-Ply® Comparison Data

